

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): N. Takano, et al.
Appln. No. Reissue Application of U.S. Patent No. 6,524,717
issued on February 25, 2003
Filed: February 4, 2004
For: PREPREG, METAL-CLAD LAMINATE, AND PRINTED
CIRCUIT BOARD OBTAINED FROM THESE

STATUS OF CLAIMS AND SUPPORT FOR CLAIM CHANGES

Mail Stop Reissue
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 4, 2004

Sir:

Pursuant to the requirements of 37 CFR § 1.173(c), the following sets forth the status of claims, and support for claim changes, in connection with the above-identified Reissue Application.

All of patent claims 1-25 of U.S. Patent No. 6,524,717 remain pending in the above-identified Reissue Application, with claim 1 (the sole independent claim in U.S. Patent No. 6,524,717) being amended. Moreover, claims 26-28 have been added in the above-identified Reissue Application as filed, as compared to the claims patented in U.S. Patent No. 6,524,717.

Patent claim 1, the sole independent claim in the above-identified application has been amended to recite that the inorganic filler is included in the resin composition in an amount of 25% by volume "or more" based on the total volume of a solid component of the resin composition. As for support of the inorganic filler being included in an amount of 25% by volume "or more", see, for example, the

paragraph bridging columns 3 and 4 of U.S. Patent No. 6,524,717 (which is the paragraph bridging columns 3 and 4 of the above-identified Reissue Application).

In addition, by the present Reissue Application, claims 26-28 are being added to the application. Claim 26, dependent on claim 1, recites that the inorganic filler is added in an amount of 25% - 65% by volume based on the total volume of the solid component of the resin composition. As for support for this claim 26, note, for example, column 4, lines 10-16 of U.S. Patent No. 6,524,717 (and of the above-identified Reissue Application). Claims 27 and 28, dependent respectively on claims 26 and 27, respectively recites a metal-clad-laminated board which includes at least one metal foil being laminated on both surfaces or on one surface of the prepreg according to claim 26, or a laminated board thereof under heating and pressure; and recites a printed wiring board which is obtained by subjecting the board of claim 27 to circuit processing. As to support for claims 27 and 28, note patent claims 11 and 13, particularly in light of the description at column 4, lines 10-16 of the specification of U.S. Patent No. 6,524,717.

It is also to be noted that the specification of the above-identified Reissue Application, as compared with the specification of U.S. Patent No. 6,524,717, has been amended under the "SUMMARY OF THE INVENTION", to indicate that the inorganic filler is included in the resin composition in an amount of 25% by volume "or more" based on the total volume of a solid component of the resin composition, consistent with the aforementioned description in the paragraph bridging columns 3 and 4 of the above-identified Reissue Application and of U.S. Patent No. 6,524,717.

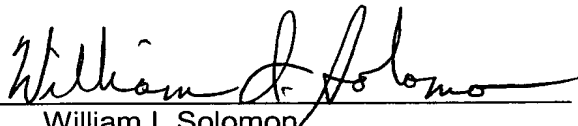
It is respectfully submitted that the foregoing constitutes the necessary statement of status of claims, as well as support for claim changes, as of the date of

filing of the above-identified Reissue Application, of all patent claims and of all added claims. See 37 CFR § 1.173(c).

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Antonelli, Terry, Stout & Kraus, LLP Deposit Account No. 01-2135 (Docket No. 511.40488RO1), and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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